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**INFORMATION DISCLOSURE  
STATEMENT BY APPLICANT**  
(use as many sheets as necessary)**COMPLETE IF KNOWN**

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Filing Date	2/4/98
First Named Inventor	Ritzdorf
Group Art Unit	2823
Examiner Name	Deven M. Collins
Attorney Docket No.	29195.8162US

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**U.S. PATENT DOCUMENTS**

*EXAMINER INITIALS*	Cite No.	U.S. Patent Document		Name of Patentee or Applicant of Cited Document	Date of Publication of Cited Document	Pages, Columns, Lines, Where Relevant Passages or Relevant Figures Appear
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**OTHER PRIOR ART-NON PATENT LITERATURE DOCUMENTS**

*EXAMINER INITIALS*	Cite No.	Include: name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume/issue number(s), publisher, city and/or country where published.
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